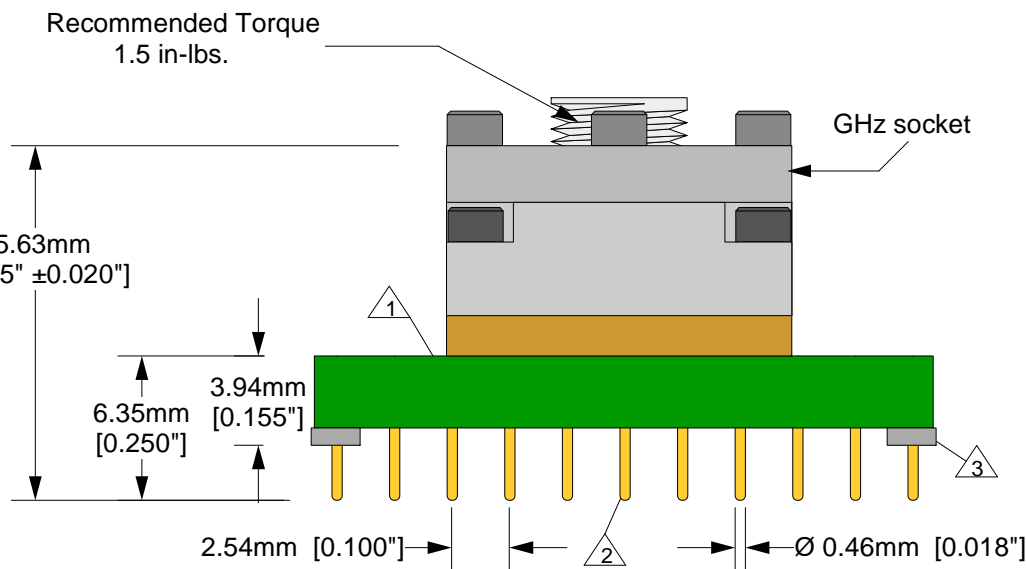


Top View



Front View

- △1 Substrate: 0.125"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △3 Stand-off: material- Teflon; 0.090" Dia; 0.030" thick.

Description: Prototyping adaptor

60 position, MLF GHz socket (-Z version) to type PGA base pins (0.100" centers).

Add "W" to end of part number for the inclusion of optional wire wrap sub base.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

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	<p>Drawing: MA Fedde</p>	<p>Date: 12/27/02</p>		<p>Modified: 4/30/14</p>